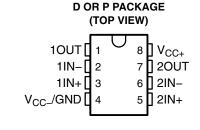
TL3472 HIGH-SLEW-RATE, SINGLE-SUPPLY OPERATIONAL AMPLIFIER

SLOS200G - OCTOBER 1997 - REVISED JULY 2003

- Wide Gain-Bandwidth Product . . . 4 MHz
- High Slew Rate . . . 13 V/μs
- Fast Settling Time . . . 1.1 μs to 0.1%
- Wide-Range Single-Supply Operation . . . 4 V to 36 V
- Wide Input Common-Mode Range Includes Ground (V_{CC})
- Low Total Harmonic Distortion . . . 0.02%
- Large-Capacitance Drive Capability . . . 10,000 pF
- Output Short-Circuit Protection



description/ordering information

Quality, low-cost, bipolar fabrication with innovative design concepts is employed for the TL3472 operational amplifier. This device offers 4 MHz of gain-bandwidth product, 13-V/ μ s slew rate, and fast settling time, without the use of JFET device technology. Although the TL3472 can be operated from split supplies, it is particularly suited for single-supply operation because the common-mode input voltage range includes ground potential (V_{CC}). With a Darlington transistor input stage, this device exhibits high input resistance, low input offset voltage, and high gain. The all-npn output stage, characterized by no dead-band crossover distortion and large output voltage swing, provides high-capacitance drive capability, excellent phase and gain margins, low open-loop high-frequency output impedance, and symmetrical source/sink ac frequency response. This low-cost amplifier is an alternative to the MC33072 and the MC34072 operational amplifiers.

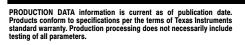
ORDERING INFORMATION

T _A	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	PDIP (P)	Tube of 25	TL3472CP	TL3472CP	
0°C to 70°C	0010 (D)	Tube of 50	TL3472CD	0.4700	
	SOIC (D)	Reel of 2500	TL3472CDR	3472C	
	PDIP (P)	Tube of 25	TL3472IP	TL3472IP	
–40°C to 105°C	COIC (D)	Tube of 50	TL3472ID	70.470	
	SOIC (D)	Reel of 2500	TL3472IDR	Z3472	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

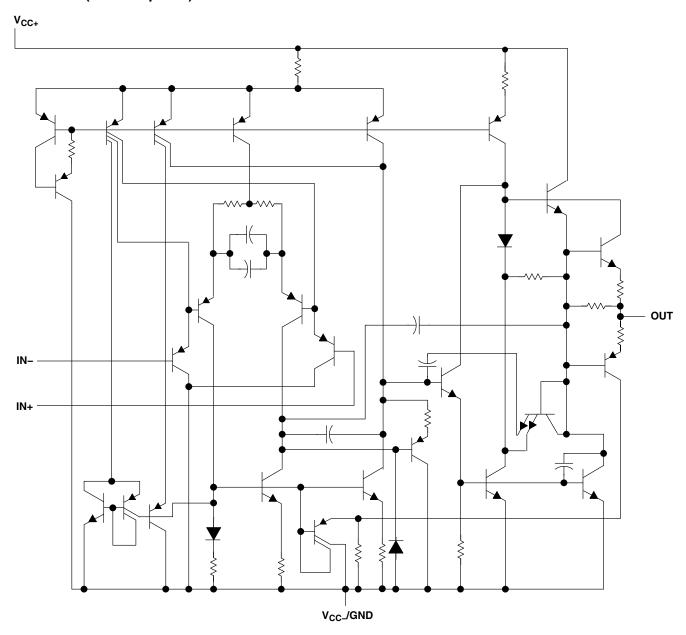


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.





schematic (each amplifier)



HIGH-SLEW-RATE, SINGLE-SUPPLY OPERATIONAL AMPLIFIER

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage (see Note 1): V _{CC+}	18 V
V _{CC-}	
Differential input voltage, V _{ID} (see Note 2)	±36 V
Input voltage, V _I (any input)	V _{CC±}
Input current, I _I (each input)	±1 mA
Output current, I _O	±80 mA
Total current into V _{CC+}	80 mA
Total current out of V _{CC-}	80 mA
Duration of short-circuit current at (or below) 25°C (see Note 3)	Unlimited
Package thermal impedance, θ_{JA} (see Notes 4 and 5): D package	97°C/W
P package	85°C/W
Operating virtual junction temperature, T _J	150°C
Lead temperature 1.6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{sta}	65°C to 150°C
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to the midpoint between V_{CC+} and V_{CC-}.
 - 2. Differential voltages are at the noninverting input with respect to the inverting input. Excessive input current can flow when the input is less than V_{CC} 0.3 V.
 - 3. The output can be shorted to either supply. Temperature and/or supply voltages must be limited to ensure that the maximum dissipation rating is not exceeded.
 - 4. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can impact reliability.
 - 5. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

			MIN	MAX	UNIT
$V_{CC\pm}$	Supply voltage		4	36	V
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	Common mode insulvellane	V _{CC} = 5 V	0	2.8	
V_{IC}	Common-mode input voltage	$V_{CC\pm} = \pm 15 \text{ V}$	-15	12.8	V
_	Onevating free circlemporature	TL3472C	0	70	°C
T _A	Operating free-air temperature TL3472I		-40	105)

TL3472 HIGH-SLEW-RATE, SINGLE-SUPPLY OPERATIONAL AMPLIFIER

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electrical characteristics at specified free-air temperature, $V_{CC\pm}$ = ± 15 V (unless otherwise noted)

	PARAMETER	TEST CONDITIONS			T _A	MIN	TYP†	MAX	UNIT
			$V_{CC} = 5 V$		25°C		1.5	10	
V _{IO}	Input offset voltage						1.0	10	mV
			$V_{CC} = \pm 15$	/	Full range [‡]			12	
$\alpha_{V_{IO}}$	Temperature coefficient of input offset voltage	$V_{IC} = 0,$ $V_{O} = 0,$	V _{CC} = ±15 \	/	Full range [‡]		10		μV/°C
	land the offers of a common to	$R_S = 50 \Omega$	V 145.	,	25°C		6	75	4
I _{IO}	Input offset current		$V_{CC} = \pm 15$ \	/	Full range [‡]			300	nA
	land black some			,	25°C		100	500	4
I _{IB}	Input bias current		$V_{CC} = \pm 15$ \	/	Full range [‡]			700	nA
Common-mode V _{ICR} input voltage range		$R_S = 50 \Omega$			25°C		–15 to 12.8		,
					Full range [‡]		-15 to 12.8		V
		$V_{CC+} = 5 V$,	$V_{CC-} = 0$,	$R_L = 2 k\Omega$	25°C	3.7	4		
V _{OH}	High-level output voltage	$R_L = 10 \text{ k}\Omega$			25°C	13.6	14		V
		$R_L = 2 k\Omega$			Full range [‡]	13.4			
		$V_{CC+} = 5 V$,	$V_{CC-} = 0$,	$R_L = 2 k\Omega$	25°C		0.1	0.3	
V _{OL}	Low-level output voltage	$R_L = 10 \text{ k}\Omega$			25°C		-14.7	-14.3	V
		$R_L = 2 k\Omega$			Full range [‡]			-13.5	
	Large-signal differential	V 140 V	D 01:0		25°C	25	100		\//\/
A _{VD}	voltage amplification	$V_{O} = \pm 10 \text{ V},$	$R_L = 2 k\Omega$		Full range [‡]	20			V/mV
	Chart singuit autout aumant	Source: V _{ID} = 1 V,	$V_O = 0$		0500	-10	-34		4
los	Short-circuit output current	Sink: $V_{ID} = -1 V$,	$V_O = 0$		25°C	20	27		mA
CMRR	Common-mode rejection ratio	$V_{IC} = V_{ICR}(min),$	$R_S = 50 \Omega$		25°C	65	97		dB
k _{SVR}	Supply-voltage rejection ratio $(\Delta V_{CC^{\pm}}\!/\Delta V_{IO})$	$V_{CC\pm} = \pm 13.5 \text{ V to } \pm$	16.5 V,	R _S = 100 Ω	25°C	70	97		dB
			= 0, No load		25°C		3.5	4.5	
Icc	Supply current (per channel)	$V_O = 0$,			Full range [‡]		4.5	5.5	mA
		$V_{CC+} = 5 \text{ V}, V_{O} = 2.5$	$5 \text{ V}, V_{\text{CC}-} = 0,$	No load	25°C		3.5	4.5	

[†] All typical values are at T_A = 25°C. ‡ Full range is 0°C to 70°C for the TL3472C device and –40°C to 105°C for the TL3472I device.

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operating characteristics, V_{CC^\pm} = ± 15 V, T_A = $25^{\circ}C$

	PARAMETER	TEST CO	TEST CONDITIONS				
SR+	Positive slew rate	$V_I = -10 \text{ V to } 10 \text{ V},$	A _V = 1	8	10		V/μs
SR-	Negative slew rate	$R_L = 2 \text{ k}\Omega, C_L = 300 \text{ pF}$	$A_V = -1$		13		V/μs
	0 1111 11	4 40 1/4	To 0.1%		1.1		
t _s	Settling time	$A_{VD} = -1$, 10-V step	To 0.01%		2.2		μs
V _n	Equivalent input noise voltage	f = 1 kHz,	R _S = 100 Ω		49		nV/√ Hz
In	Equivalent input noise current	f = 1 kHz		0.22		pA/√ Hz	
THD	Total harmonic distortion	$V_{O(PP)} = 2 \text{ V to } 20 \text{ V}, R_L = 2$		0.02		%	
GBW	Gain-bandwidth product	f =100 kHz	3	4		MHz	
BW	Power bandwidth	$V_{O(PP)} = 20 \text{ V}, R_L = 2 \text{ k}\Omega, A_V$	_D = 1, THD = 5.0%		160		kHz
	Dharanain	D 010	C _L = 0	70			
φm	Phase margin	$R_L = 2 k\Omega$	C _L = 300 pF		50		deg
		B 010	C _L = 0	12			
	Gain margin	$R_L = 2 k\Omega$	C _L = 300 pF		4		dB
rį	Differential input resistance	V _{IC} = 0		150		MΩ	
C _i	Input capacitance	V _{IC} = 0			2.5		pF
	Channel separation	f = 10 kHz			101		dB
z _o	Open-loop output impedance	f = 1 MHz,	A _V = 1		20		Ω







PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL3472CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3472CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3472CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3472CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3472CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3472CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3472CP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL3472CPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL3472ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3472IDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3472IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3472IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3472IDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3472IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3472IP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL3472IPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

18-Sep-2008

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF TL3472:

• Automotive: TL3472-Q1

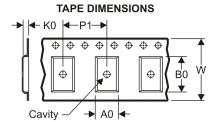
NOTE: Qualified Version Definitions:

• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

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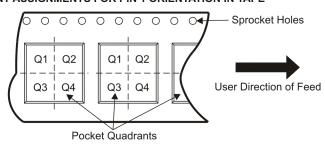
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

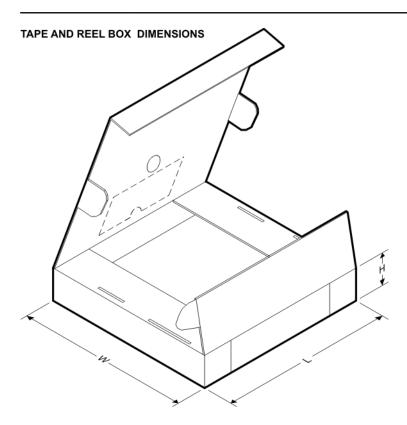
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

All difficultions are norminal												
Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL3472CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL3472CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL3472IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL3472IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

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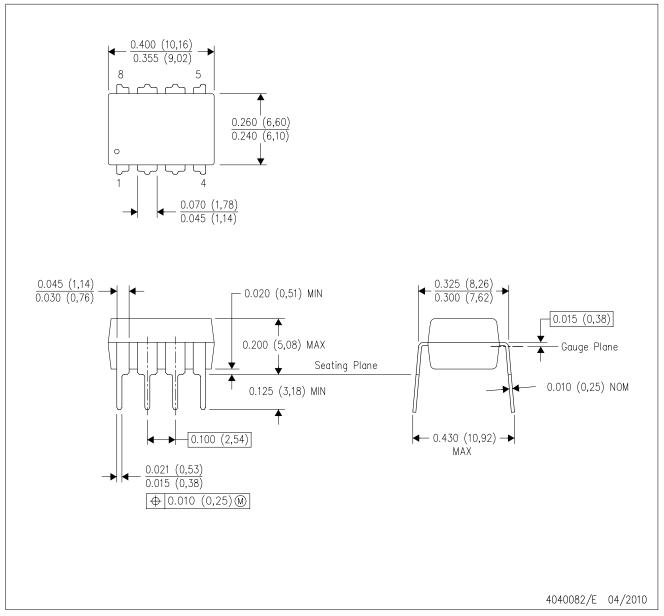


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL3472CDR	SOIC	D	8	2500	346.0	346.0	29.0
TL3472CDR	SOIC	D	8	2500	340.5	338.1	20.6
TL3472IDR	SOIC	D	8	2500	340.5	338.1	20.6
TL3472IDR	SOIC	D	8	2500	346.0	346.0	29.0

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



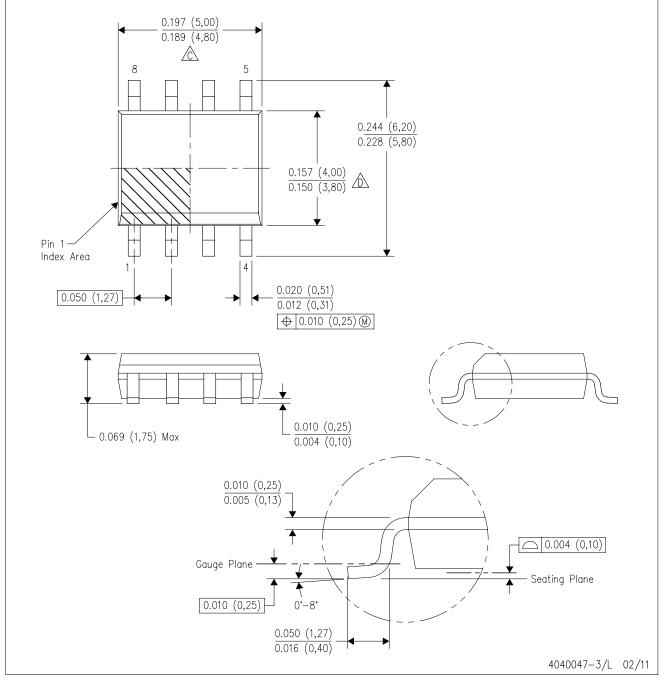
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



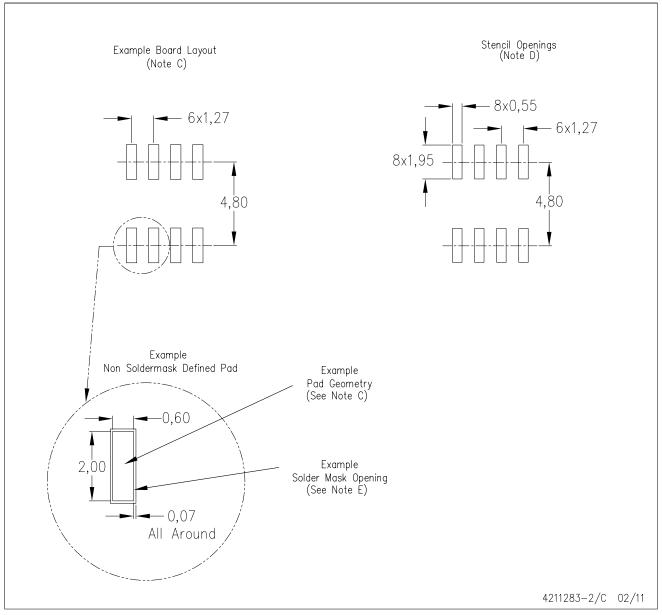
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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